

PROCEEDINGS OF SPIE

Micromachining and Microfabrication Process Technology XVIII

**Mary Ann Maher
Paul J. Resnick**
Editors

**5 and 7 February 2013
San Francisco, California, United States**

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Published by
SPIE

Volume 8612

Proceedings of SPIE 0277-786X, V.8612

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Micromachining and Microfabrication Process Technology XVIII, edited by Mary Ann Maher, Paul J. Resnick,
Proc. of SPIE Vol. 8612, 861201 · © 2013 SPIE · CCC code: 0277-786X/13/\$18 · doi: 10.1117/12.2022901

Proc. of SPIE Vol. 8612 861201-1

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Author(s), "Title of Paper," in *Micromachining and Microfabrication Process Technology XVIII*, edited by Mary Ann Maher, Paul J. Resnick, Proceedings of SPIE Vol. 8612 (SPIE, Bellingham, WA, 2013) Article CID Number.

ISSN: 0277-786X

ISBN: 9780819493811

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445

SPIE.org

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Printed in the United States of America.

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